



# Providing Optimal Semiconductor Solutions Worldwide

## Company Overview

In February 2005, Mimix Broadband, Inc. acquired a majority stake in Hocom Communications, Inc., a MMIC test, inspection and packaging operation based in Hsinchu, Taiwan. "Mimix Asia," as it is now known, provides strategic support to Mimix Broadband for production, supply chain management, order processing and fulfillment. Mimix Asia also designs and develops monolithic microwave integrated circuits (MMICs) for microwave and millimeter-wave applications.

## Facility and Capabilities:

The Mimix Asia facility includes a Class 10,000 clean room for die picking and visual inspection that gives Mimix access to 8,000 square feet of production floor space in Hsinchu Science-Based Industrial Park, which is in close proximity to some of Mimix's wafer fabrication and other production partners. This strategic location reduces production cycle time and expedites delivery to Mimix customers.

## Company Highlights:

- ✕ Established in April 1999
- ✕ Acquired by Mimix Broadband - February 2005
- ✕ Achieved ISO 9001 registration - April 2005
- ✕ Name changed to Mimix Asia - January 2006
- ✕ Began module assembly - April 2006
- ✕ Began on-wafer RF testing - October 2006

## Quality Assurance:

Mimix Asia integrates quality into all business processes. Beginning with our ISO 9001-registered quality management system, which includes our comprehensive design and manufacturing processes, and extending throughout the company, each employee is empowered to continually identify and implement improvements that enhance product quality and customer satisfaction. We extend this same philosophy to our subcontractors and suppliers, including our ISO 9001-registered foundries and our packaging providers.



For more information visit us on the web at [www.mimixasia.com](http://www.mimixasia.com)

## Products

Our MMIC Product Matrix contains a snapshot view of our current product line. As Mimix Asia strives to provide extensive applications engineering support and customer service, the product development categories for our MMIC devices should help design engineers understand our nomenclature.

- Production Devices
- Pre-production Devices
- D - Defense

To obtain a complete datasheet of any product, please visit [www.mimixasia.com](http://www.mimixasia.com) or contact us via email at [info@mimixasia.com](mailto:info@mimixasia.com) to request a copy.

Power Amplifiers									
Description	Part #	Frequency (GHz)	Gain (dB)	Gain Flatness (dB)	Output P1dB (dBm)	Bias (mA @ V)	Package	Applications	
Power Amplifier	XP1006-BD	8.5-11.0	21.0	+/-0.5	+40.0 (P <sub>sat</sub> )	4.2 A @ 8.0	DIE	D	
Power Amplifier	XP1006-FA	8.5-11.0	21.5	+/-0.5	+40.5 (P <sub>sat</sub> )	4.2 A @ 8.0	-FA (Flange)	D	
Power Amplifier	XP1014-BD	8.5-11.0	18.0	+/-1.0	+31.0 (P <sub>sat</sub> )	450 @ 8.0	DIE	D	
Power Amplifier	XP1014-SM	8.5-11.0	18.0	+/-1.0	+31.0 (P <sub>sat</sub> )	450 @ 8.0	-SM (6x6 mm)	D	

  

Attenuators									
Description	Part #	Frequency (GHz)	Attn Range (dB)	Step Size (dB)	Insertion Loss (dB)	Return Loss (dB)	Bias (mA @ V)	Package	Applications
5-Bit Digital Attenuator	XA1000-BD	DC-18.0	28	0.9	3-7	15	9 @ -7.5	DIE	D
5-Bit Digital Attenuator	XA1000-OH	DC-18.0	28	0.9	3-7	15	9 @ -7.5	-OH (4x4 mm)	D

  

Phase Shifters									
Description	Part #	Frequency (GHz)	Step Size (deg)	Insertion Loss (dB)	Return Loss (dB)	Input P1dB (dBm)	Bias (mA @ V)	Package	Applications
6-Bit Digital Phase Shifter	XS1001-BD	2.5-4.0	5.625	6	15	+26	9 @ -10.0	DIE	D
6-Bit Digital Phase Shifter	XS1001-QK	2.5-4.0	5.625	6	12	+26	9 @ -10.0	-QK (7x7 mm)	D
6-Bit Digital Phase Shifter	XS1000-BD	7.0-13.0	5.625	6	15	+25	9 @ -7.5	DIE	D
6-Bit Digital Phase Shifter	XS1000-QK	7.0-13.0	5.625	6.5	12	+25	9 @ -7.5	-QK (7x7 mm)	D

  

Core Chips											
Description	Part #	Frequency (GHz)	Gain (Rx/Tx) (dB)	Input / Output (Rx/Tx) P1dB (dBm)	IIP3 (dBm)	Rx NF (dB)	5-Bit Attn Step/Range (dB)	6-Bit Phase Step Size (deg)	Bias (mA @ V)	Package	Applications
S-Band Core (Receive / Transmit)	XZ1001-BD	2.5-4.0	26.0 / 26.0	-13.0 / +14.0	-3.0	2.2	0.9 / 28	5.625	200 @ 5V 20 @ -10V	DIE	D
X-Band Core (Receive / Transmit)	XZ1002-BD	8.5-11.0	20.0 / 20.0	-10.0 / +20.0	0.0	4.0	0.9 / 28	5.625	200 @ 4V 20 @ -5V	DIE	D